CHIPQUIK®

NCSWLF.015 0.20Z

Datasheet revision 1.0 <u>www.chipquik.com</u>

Solder Wire SAC305 No-Clean with 2.0% Flux Core 0.2oz Tube

Product Highlights

No-Clean Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board.

2.0% flux core

Halogen content: None

RoHS 3 and REACH compliant



Alloy: Sn96.5/Ag3.0/Cu0.5 Wire Diameter: 0.015" (0.38mm) Flux Type: No-Clean Synthetic

Flux Classification: ROL0

Melting Point: 217-220°C (423-428°F)

Packaging: 0.2 oz Tube



Test Results

1 CSt RCSuitS		
Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship	Compliant
	Coalition (EICC)	
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes